| ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INFORMATION CONNECTING | PC. Bannockl | ourn. Illinois. A | Ill rights reserved untions. | under both | This docum level parts, t | ent is a declara | tion of the encompass | substances es all lowe | within the er level ma | e manufacture terials for wh | er listed it hich the m | em. Note: anufactur | if the item is an a er has engineering | ssembly with lower responsibility. |
|---|--|-------------------|------------------------------|----------------------|------------------------------|---|-------------------------------|---------------------------|-----------------------------|---------------------------------|----------------------------|------------------------|--|---------------------------------------|
| | IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distri | | | | * | * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M | | | | | als and M | fg Inform | ation | |
| Supplier Information | | | | | | | | | | | | | | |
| Company name* Co | | | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | |
| onsemi | | | | | | | | | | | 2024-05-18 | | | |
| Contact Name Title - Contac | | | itact | | | Phone - Contact* | | | | Email - Contact* | | | | |
| Product-Env-Stewards Product | | | oduct Enviro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title - Rep | | | Representative | | | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-Stewards Product I | | | duct Enviro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Iten | n Number | Mfr Item Name | | | Effective Da | e Versior | sion Manufacturing Site | | ring Site | | Weight* | UOM | Unit Type |
| | NRVUA | .110VT3G | REC SMA 1A 100V ULTFST TR | | R | 2024-05-18 | | | VN5 | | 7 | 76.66 | mg | Each |
| Manufacturing Proccess Informa | tion | | | | | | | | | | | | | |
| Terminal Plating / Grid Array M | al Plating / Grid Array Material Terminal Base . | | Alloy | J-STD-020 MSL Rating | | Peak Pro | Peak Process Body Temperature | | re Max Time at Peak Tempera | | Temperat | ure Nun | nber of Reflow Cy | cles |
| Matte Tin (Sn) - annealed CU Alloy | | CU Alloy | | 1 | | 260 | | С | 30 | | secon | ds 3 | | |
| Comments | | | | | | | | | | | | | | |
| evel 1 - maximum time at peak temperat | ure during so | Idering is 10-3 | 0 seconds | | | | | | | | | | | |
| or more information regarding material | composition | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declar | ation | | | Declaration Type * | Detailed |
|---|---|--|--|---|---|
| Directive 2015/863/EU amending Rol Directive 2011/65/EU | (Pb), Mercury (Hg), Hexav | | ninated Biphenyls (PBB), Polybror | dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth | |
| cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co | rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili | ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for | toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform | ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of |
| RoHS Declaration * 4 | - Item(s) does not contain RoHS restr | icted substances per the definition | above except for selected exempti | ons Supplier Acceptance | * Accepted |
| Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect | g temperature type solders (i.e. lead ronic components containing lead i | l based solder alloys containing n a glass or ceramic other than | 85% by weight or more lead). dielectric ceramic in capacitors, o | e.g. piezoelectronic devices, or in a glass or ce | eramic matrix compound. |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| Instructions: Complete all of the rec Requester) and click on Submit For | | | Supplier Acceptance drop-down | . This will display the signature area. Digital | ly sign the declaration (if required by the |
| Supplier Digital Signature | Rastislav Drska | Le | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|------------------------------|------------|--------|---------|-----------------|
| Clip | 7.0 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0084 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.1645 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 6.825 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0021 | mg |
| Die | 1.12 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 1.1088 | mg |
| | | | Supplier | Lead Bisilicate | 65997-18-4 | 7c | 0.0112 | mg |
| Die Attach Solder | 3.45 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0862 | mg |
| | | | А | Lead (Pb) | 7439-92-1 | 7a | 3.1913 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.1725 | mg |
| Lead Frame | 28.84 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0346 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.6922 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 28.0902 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0231 | mg |
| Mold Compound-Black | 34.87 | mg | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 3.487 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.1743 | mg |
| | | | Supplier | Aluminum Hydroxide (Al(OH)3) | 21645-51-2 | | 5.0561 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 22.6655 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 3.487 | mg |
| Plating | 1.38 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 1.38 | mg |